

Silicon Carbide (SiC) **Schottky Diode** - EliteSiC, 20 A, 650 V, D1, TO-247-2L

FFSH2065A

Description

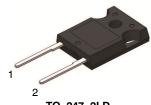
Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 95 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery
- This Device is Pb-Free and is RoHS Compliant

Applications

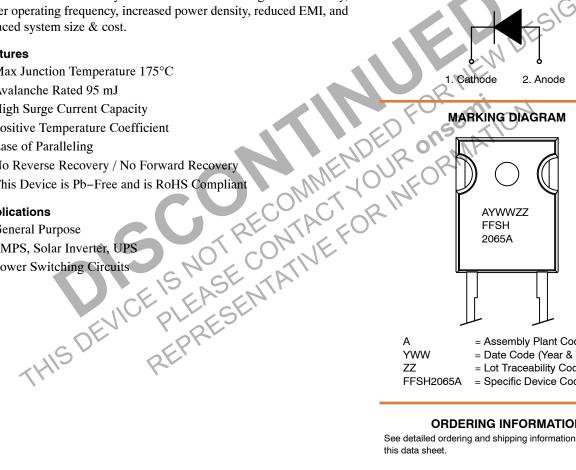
- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits



TO-247-2LD CASE 340CL

V _{RRM}	I _F	
650 V	20 A	





= Assembly Plant Code = Date Code (Year & Week) = Lot Traceability Code = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise specified)

Symbol	Parameter		FFSH2065A	Unit
V_{RRM}	Peak Repetitive Reverse Voltage		650	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		95	mJ
l _F	Continuous Rectified Forward Current	@ Tc < 146°C	20	Α
		@ Tc < 135°C	25	
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	Tc = 25°C, 10 μs	1100	Α
		Tc = 150°C, 10 μs	1000	Α
I _{F, SM}	Non-Repetitive Forward Surge Current	Half-Sine Pulse, tp = 8.3 ms	105	Α
I _{F, RM}	Repetitive Forward Surge Current	Half-Sine Pulse, tp = 8.3 ms	58	Α
P _{tot}	Power Dissipation	Tc = 25°C	183	W
		Tc = 150°C	31	W
T _J , T _{STG}	Operating and Storage Temperature Range	•	-55 to +175	√,c
	TO247 Mounting Torque, M3 Screw		60	Ncm

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. E_{AS} of 95 mJ is based on starting $T_J = 25^{\circ}C$, L = 0.5 mH, $I_{AS} = 19.5$ A, V = 50 V.

THERMAL CHARACTERISTICS

Symbol	Parameter	Rating Unit
$R_{ hetaJC}$	Thermal Resistance, Junction to Case, Max.	0.82 °C/W

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _F	Forward Voltage	IF = 20 A, Tc = 25°C	-	1.50	1.75	V
		IP = 20 A, Tc = 125°C	-	1.6	2.0	
	15	IF = 20 A, To = 175°C	-	1.72	2.4	
I _R	Reverse Current	VR = 650 V, Tc = 25°C	-	-	200	μΑ
	119,05	VR = 650 V, Tc = 125°C	-	-	400	
	INCLUSE SE	VR = 650 V, Tc = 175°C	-	-	600	
Q _C	Total Capacitive Charge	V = 400 V	-	64	-	nC
С	Total Capacitance	VR = 1 V, f = 100 kHz	-	1085	-	pF
14	K	VR = 200 V, f = 100 kHz	-	117	-	
		VR = 400 V, f = 100 kHz	_	88	-	

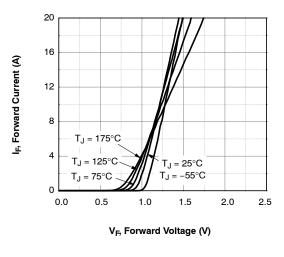
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
FFSH2065A	FFSH2065A	TO-247-2LD	30 Units / Tube

TYPICAL CHARACTERISTICS

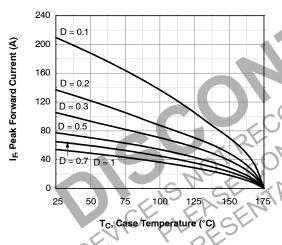
(T_J = 25°C UNLESS OTHERWISE NOTED)



10⁻⁵ 10^{-6} I_R, Reverse Current (A) $T_J = 25^{\circ}C$ 10^{-7} $T_J = 175^{\circ}C$ T_J = 125°C 10^{-8} T_J = 75°C $T_J = -55^{\circ}C$ 10⁻⁹ 200 300 500 600 650 V_R, Reverse Voltage (V)

Figure 1. Forward Characteristics

Figure 2. Reverse Characteristics



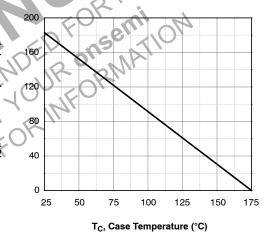
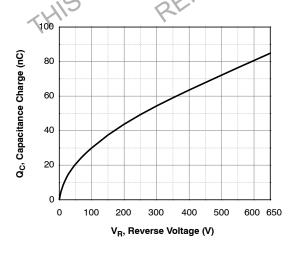


Figure 3. Current Derating

Figure 4. Power Derating



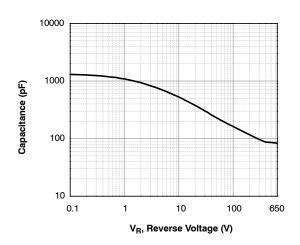


Figure 5. Capacitive Charge vs. Reverse Voltage

Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS (CONTINUED)

(T_J = 25°C UNLESS OTHERWISE NOTED)

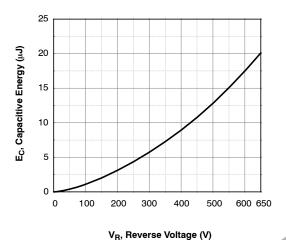
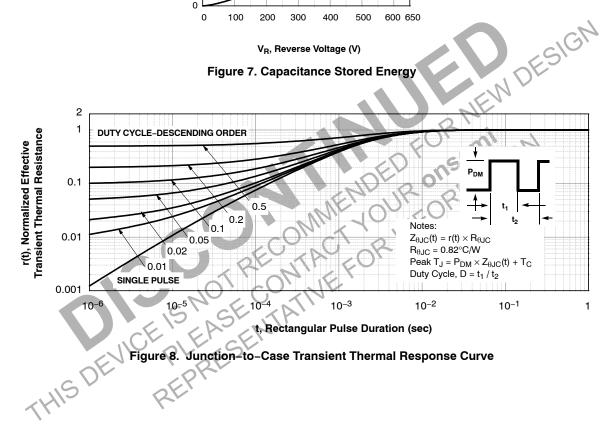
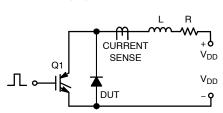


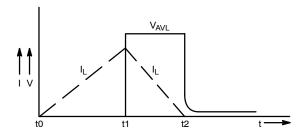
Figure 7. Capacitance Stored Energy



TEST CIRCUIT AND WAVEFORMS

$$\label{eq:local_local_local} \begin{split} L &= 0.5 \text{ mH} \\ R &< 0.1 \ \Omega \\ V_{DD} &= 50 \ V \\ EAVL &= 1/2 LI2 \left[V_{R(AVL)} / (V_{R(AVL)} - V_{DD}) \right] \\ Q1 &= IGBT \left(BV_{CES} > DUT \ V_{R(AVL)} \right) \end{split}$$



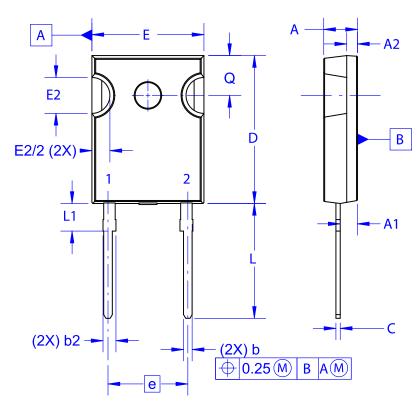


THIS DEVICE PLEASE NTATIVE FOR INFORMATION REPRESENTATIVE FOR INFORMATION

DATE 03 DEC 2019



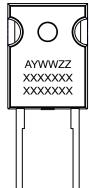






- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
 D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

= Assembly Location

= Year

= Work Week WW

= Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

Ø P —		Ø P1 D2
E1 —		D1
		J

DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
A1	2.29	2.40	2.66	
A2	1.30	1.50	1.70	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
С	0.51	0.61	0.71	
D	20.32	20.57	20.82	
D1	16.37	16.57	16.77	
D2	0.51	0.93	1.35	
Е	15.37	15.62	15.87	
E1	12.81	~	~	
E2	4.96	5.08	5.20	
е	~	11.12	~	
L	15.75	16.00	16.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
Ø P 1	6.61	6.73	6.85	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	

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DESCRIPTION:	TO-247-2LD		PAGE 1 OF 1

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